



Material Content Data Sheet



Sales Product Name		BGS 12AL7-6 E6327		Issued		25. September 2017		
MA#		MA000601996						
Package		PG-TSLP-7-6		Weight*		1.52 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.158	10.34	10.34	103410	103410
leadframe	non noble metal	nickel	7440-02-0	0.329	21.58	21.58	215761	215761
wire	noble metal	gold	7440-57-5	0.030	1.95	1.95	19467	19467
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.03		279	
	organic material	carbon black	1333-86-4	0.009	0.56		5579	
	plastics	epoxy resin	-	0.115	7.53		75314	
encapsulation	inorganic material	silicondioxide	60676-86-0	0.726	47.66	55.78	476707	557879
	noble metal	gold	7440-57-5	0.032	2.08	2.08	20761	20761
plating	noble metal	silver	7440-22-4	0.052	3.39	3.39	33902	33902
tape	plastics	acryl-epoxy resin	-	0.074	4.88	4.88	48820	48820
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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